

ヘキサ・シュミット・トリガ・インバータ

1 特長

- 2V～6V の V_{CC} で動作
- 6V までの入力電圧に対応
- 最大 t_{pd} : 9.5ns (5V 時)

2 アプリケーション

- 反転クロック入力の同期
- スイッチのデバウンス
- デジタル信号の反転

3 概要

これらのシュミット・トリガ・デバイスには、6 つの独立したインバータがあります。

パッケージ情報

部品番号	パッケージ	本体サイズ (公称)
SNx4AC14	SOIC	8.65mm × 3.9mm
	SSOP	6.2mm × 1.95mm
	PDIP	19.3mm × 6.35mm
	SOP	10.3mm × 5.3mm
	TSSOP	5.00mm × 4.4mm



論理図 (正論理)



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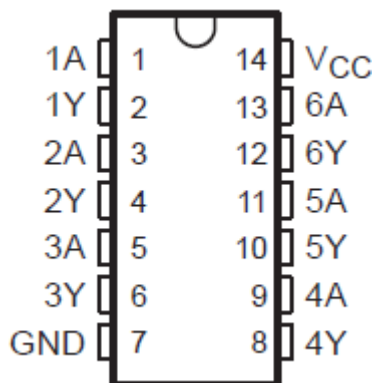
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4 Revision History

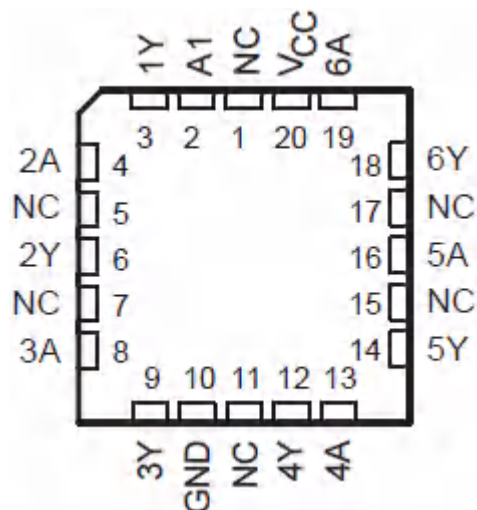
資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision G (August 2008) to Revision H (January 2023)	Page
「アプリケーション」セクション、「製品情報」表、「ピンの機能」表、「ESD 定格」表、「熱に関する情報」表、「代表的特性」セクション、「機能説明」セクション、「デバイスの機能モード」セクション、「アプリケーションと実装」セクション、「電源に関する推奨事項」セクション、「レイアウト」セクション、「デバイスおよびドキュメントのサポート」セクション、「メカニカル、パッケージ、および注文情報」セクションを追加.....	1

5 Pin Configuration and Functions



✎ 5-1. SN54AC14 J or W Package and SN74AC14 D, DB, N, NS, or PW Package Top View



NC – No internal connection

✎ 5-2. SN54AC14 FK Package Top View

Pin Functions

PIN			I/O	DESCRIPTION
NAME	D, DB, N, NS, PW, J, or W	FK		
1A	1	2	Input	Channel 1, Input A
1Y	2	3	Output	Channel 1, Output Y
2A	3	4	Input	Channel 2, Input A
2Y	4	6	Output	Channel 2, Output Y
3A	5	8	Input	Channel 3, Input A
3Y	6	9	Output	Channel 3, Output Y
GND	7	10	—	Ground
4Y	8	12	Output	Channel 4, Output Y
4A	9	13	Input	Channel 4, Input A
5Y	10	14	Output	Channel 5, Output Y
5A	11	16	Input	Channel 5, Input A
6Y	12	18	Output	Channel 6, Output Y
6A	13	19	Input	Channel 6, Input A
V _{CC}	14	20	—	Positive Supply
NC		1, 5, 7, 11, 15, 17	—	Not internally connected

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted⁽¹⁾)

		UNIT
Supply voltage range, V_{CC}	-0.5 V to 7	V
Input voltage range, V_I ⁽²⁾	-0.5 V to $V_{CC} + 0.5$	V
Output voltage range, V_O ⁽²⁾	-0.5 V to $V_{CC} + 0.5$	V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20	mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	± 20	mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50	mA
Continuous current through V_{CC} or GND	± 200	mA
Storage temperature range, T_{stg}	-65 to 150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	± 4000
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	± 2000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommend Operating Conditions

			SN54AC14		SN74AC14		UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		2	6	2	6	V
V _I	Input voltage		0	V _{CC}	0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 3 V			-12		mA
		V _{CC} = 4.5 V			-24		
		V _{CC} = 5.5 V			-24		
I _{OL}	Low-level output current	V _{CC} = 3 V			12		mA
		V _{CC} = 4.5 V			24		
		V _{CC} = 5.5 V			24		
T _A	Operating free-air temperature		-55	125	-40	85	°C

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SNx4AC14					UNIT
		D (SOIC)	DB (SSOP)	N (PDIP)	NS (SO)	PW (TSSOP)	
		14 PINS					
R _{θJA}	Junction-to-ambient thermal resistance	86	96	80	76	113	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{T+} Positive-going threshold		3 V	0.8	1.8	2.2	0.8	2.2	0.8	2.2	V
		4.5 V	1.5	2.6	3.2	1.5	3.2	1.5	3.2	
		5.5 V	1.6	3.2	3.9	1.6	3.9	1.6	3.9	
V _{T-} Negative-going threshold		3 V	0.5	0.8	1	0.5	1.2	0.5	1	V
		4.5 V	0.9	1.4	1.8	0.9	1.8	0.9	1.8	
		5.5 V	1.1	1.8	2.3	1.1	2.3	1.1	2.3	
ΔV_T Hysteresis (V _{T+} - V _{T-})		3 V	0.3	1	1.2	0.3	1.2	0.3	1.2	V
		4.5 V	0.4	1.2	1.4	0.4	1.4	0.4	1.4	
		5.5 V	0.5	1.4	1.6	0.5	1.6	0.5	1.6	
V _{OH}	I _{OH} = -50 μ A	3 V	2.9			2.9		2.9		V
		4.5 V	4.4			4.4		4.4		
		5.5 V	5.4			5.4		5.4		
	I _{OH} = -12 mA	3 V	2.56			2.4		2.48		
		4.5 V	3.86			3.7		3.8		
		5.5 V	4.86			4.7		4.8		
	I _{OH} = -50 mA ⁽¹⁾	5.5 V				3.85				
	I _{OH} = -75 mA ⁽¹⁾							3.85		
V _{OL}	I _{OL} = 50 μ A	3 V			0.1		0.1		0.1	V
		4.5 V			0.1		0.1		0.1	
		5.5 V			0.1		0.1		0.1	
	I _{OL} = 12 mA	3 V			0.36		0.44		0.44	
	I _{OL} = 24 mA	4.5 V			0.36		0.44		0.44	
		5.5 V			0.36		0.44		0.44	
	I _{OL} = 50 mA ⁽¹⁾	5.5 V					1.65			
	I _{OL} = 75 mA ⁽¹⁾							1.65		
I _I	V _I = V _{CC} or GND	5.5 V			± 0.1		± 1		± 1	μ A
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			2		40		20	μ A
C _i	V _I = V _{CC} or GND	5 V		4.5						pF

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

6.6 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	1.5	6	13.5	1	16	1.5	15	ns
t _{PHL}			1.5	6	11.5	1	14	1.5	13	

6.7 Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			SN54AC14		SN74AC14		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{PLH}	A	Y	1.5	5	10	1.5	12	1.5	11	ns
t_{PHL}			1.5	5	8.5	1.5	10	1.5	9.5	

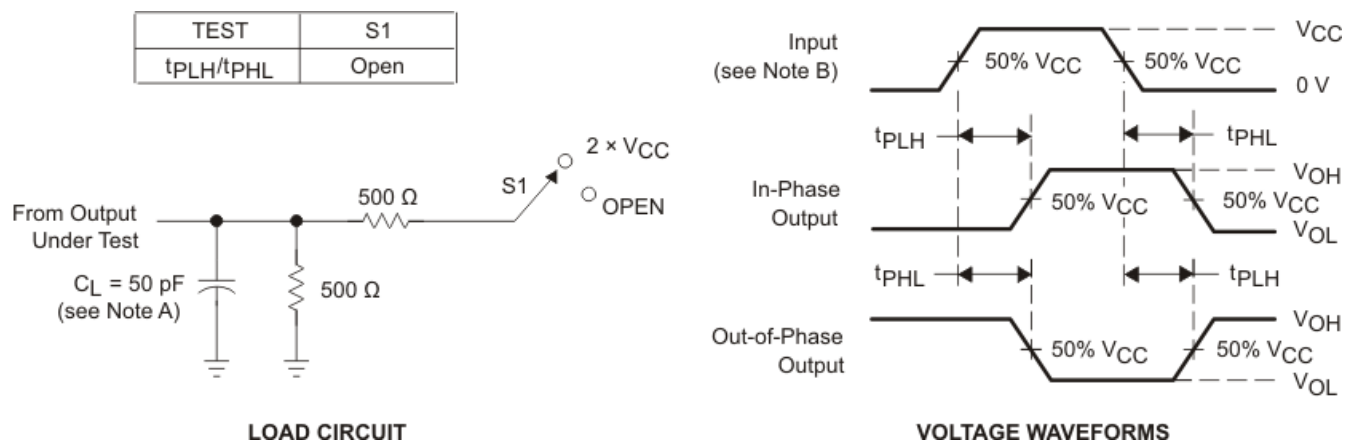
6.8 Operating Characteristics

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 1\text{ MHz}$	25	pF

7 Parameter Measurement Information

7.1



- A. C_L includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
- C. The outputs are measured one at a time with one input transition per measurement.

7-1. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

These 'AC14 devices perform the Boolean function $Y = \bar{A}$. Because of the Schmitt action, they have different input threshold levels for positive-going (V_{T+}) and for negative-going (V_{T-}) signals.

These circuits are temperature compensated and can be triggered from the slowest of input ramps and still give clean, jitter-free output signals. They also have a greater noise margin than conventional inverters.

8.2 Functional Block Diagram



8.3 Feature Description

- V_{CC} is optimized at 5 V
- Allows up voltage translation from 3.3 V to 5 V
 - Inputs accept V_{IH} levels of 2 V
- Slow edge rates minimize output ringing
- Inputs are TTL-Voltage compatible

8.3.1 Balanced CMOS Push-Pull Outputs

This device includes balanced CMOS push-pull outputs. The term *balanced* indicates that the device can sink and source similar currents. The drive capability of this device may create fast edges into light loads, so routing and load conditions should be considered to prevent ringing. Additionally, the outputs of this device are capable of driving larger currents than the device can sustain without being damaged. It is important for the output power of the device to be limited to avoid damage due to overcurrent. The electrical and thermal limits defined in the *Absolute Maximum Ratings* must be followed at all times.

Unused push-pull CMOS outputs should be left disconnected.

8.3.2 Clamp Diode Structure

As shown in [Figure 8-1](#), the inputs and outputs to this device have both positive and negative clamping diodes.

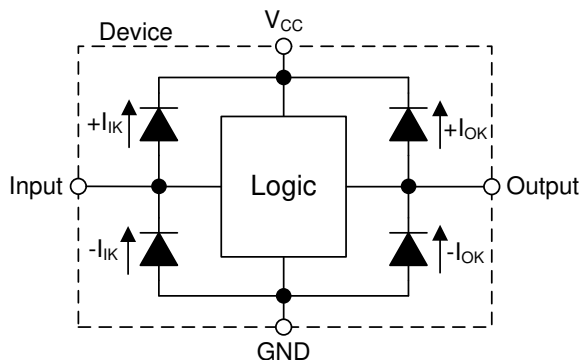
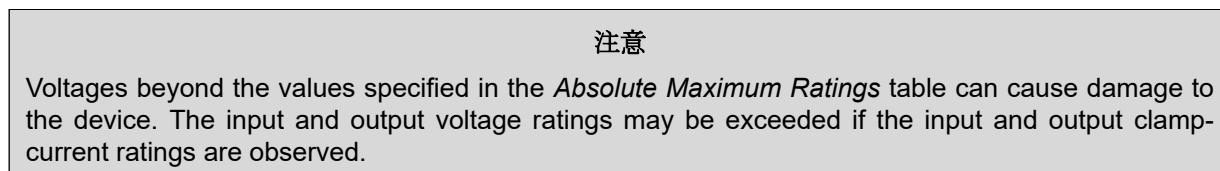


Figure 8-1. Electrical Placement of Clamping Diodes for Each Input and Output

8.4 Device Functional Modes

表 8-1. Function Table

INPUT	OUTPUT
A	Y
H	L
L	H

9 アプリケーション情報に関する免責事項

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

9.1 Application Information

The SNx4AC14 device is a low-drive CMOS device that can be used for a multitude of bus interface type applications where putput ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The inputs are tolerant to 5.5 V at any valid V_{CC} . This feature makes it Ideal for translating down to the V_{CC} level. [Switching Characteristics Comparison](#) shows the reduction in ringing compared to higher drive parts such as AC.

9.2 Typical Application

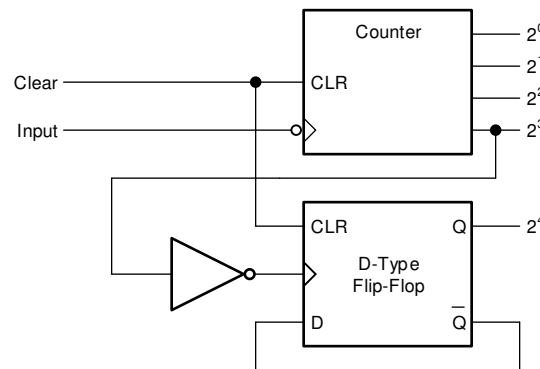


図 9-1. Typical Application Schematic

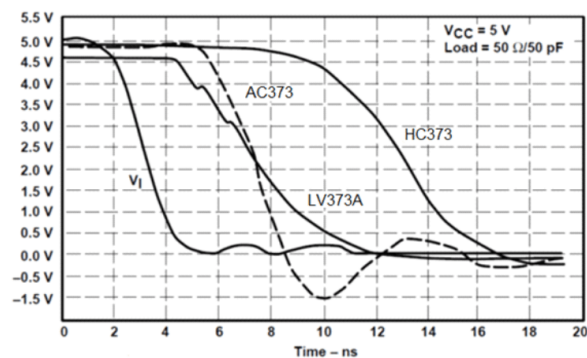
9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

9.2.2 Detailed Design Procedure

1. Recommended Input Conditions
 - For rise time and fall time specifications, see $\Delta t/\Delta V$ in the [セクション 6.3](#) table.
 - For specified High and low levels, see V_{IH} and V_{IL} in the [セクション 6.3](#) table.
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC} .
2. Recommend Output Conditions
 - Load currents should not exceed 35 mA per output and 70 mA total for the part.
 - Outputs should not be pulled above V_{CC} .

9.2.3 Application Curves



9-2. Switching Characteristics Comparison

9.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [セクション 6.3](#).

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 μF is recommended; if there are multiple V_{CC} pins, then 0.01 μF or 0.022 μF is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 μF and a 1 μF are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

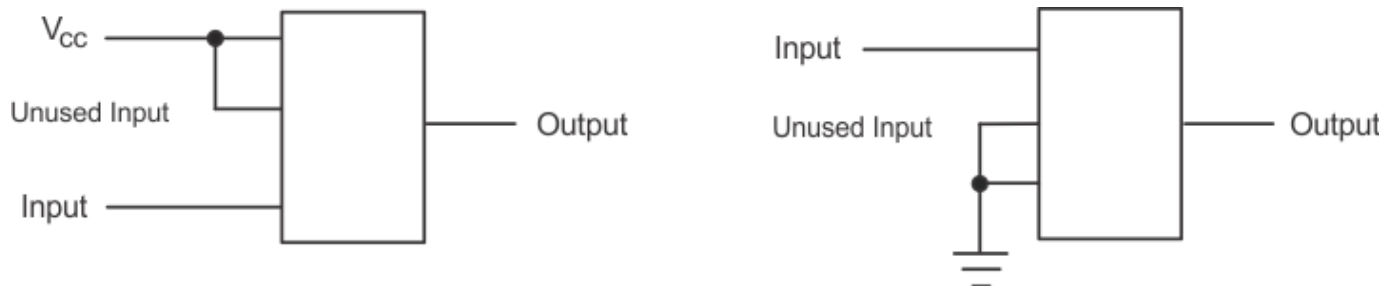
9.4 Layout

9.4.1 Layout Guidelines

When using multiple bit logic devices, inputs should not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Layout Diagram](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} , whichever makes more sense or is more convenient. It is acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, it will disable the outputs section of the part when asserted. This will not disable the input section of the I/Os so they also cannot float when disabled.

9.4.2 Layout Example



9-3. Layout Diagram

10 Device and Documentation Support

10.1 Documentation Support

10.1.1 Related Documentation

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

表 10-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
SN54AC14	Click here	Click here	Click here	Click here	Click here
SN74AC14	Click here	Click here	Click here	Click here	Click here

10.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、[ti.com](https://www.ti.com) のデバイス製品フォルダを開いてください。「更新の通知を受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

10.3 サポート・リソース

TI E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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10.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

10.5 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

10.6 用語集

[テキサス・インスツルメンツ用語集](#)

この用語集には、用語や略語の一覧および定義が記載されています。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-87624012A	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87624012A SNJ54AC 14FK	Samples
5962-8762401CA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401CA SNJ54AC14J	Samples
5962-8762401DA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401DA SNJ54AC14W	Samples
5962-8762401VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401VC A SNV54AC14J	Samples
5962-8762401VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401VD A SNV54AC14W	Samples
5962-8762402VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762402VC A SNV54AC14J	Samples
5962-8762402VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762402VD A SNV54AC14W	Samples
SN74AC14DBR	ACTIVE	SSOP	DB	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	Samples
SN74AC14DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	Samples
SN74AC14N	ACTIVE	PDIP	N	14	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74AC14N	Samples
SN74AC14NSR	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	Samples
SN74AC14NSRG4	ACTIVE	SO	NS	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	Samples
SN74AC14PWR	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AC14	Samples
SNJ54AC14FK	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 87624012A SNJ54AC 14FK	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54AC14J	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401CA SNJ54AC14J	Samples
SNJ54AC14W	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8762401DA SNJ54AC14W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54AC14, SN54AC14-SP, SN74AC14 :

- Catalog : [SN74AC14](#), [SN54AC14](#)
- Automotive : [SN74AC14-Q1](#), [SN74AC14-Q1](#)
- Military : [SN54AC14](#)
- Space : [SN54AC14-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



*All dimensions are nominal

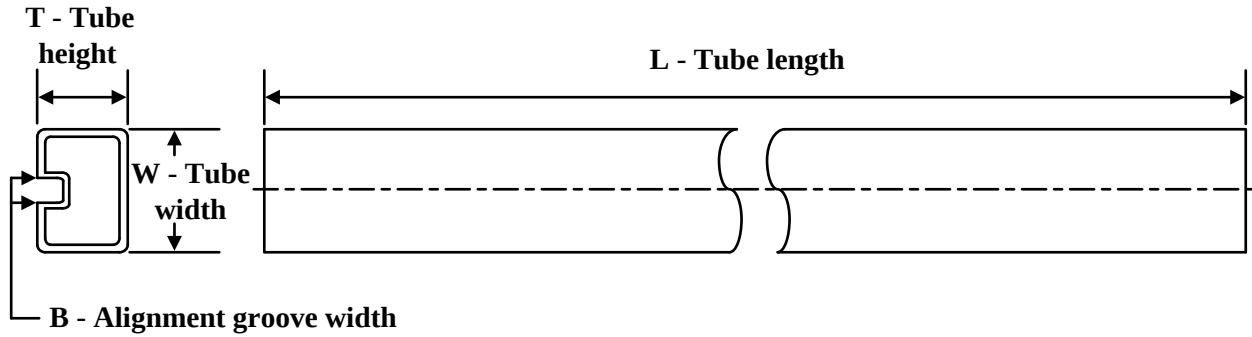
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC14DBR	SSOP	DB	14	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74AC14DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC14DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AC14NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AC14PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC14DBR	SSOP	DB	14	2000	356.0	356.0	35.0
SN74AC14DR	SOIC	D	14	2500	333.2	345.9	28.6
SN74AC14DR	SOIC	D	14	2500	356.0	356.0	35.0
SN74AC14NSR	SO	NS	14	2000	356.0	356.0	35.0
SN74AC14PWR	TSSOP	PW	14	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

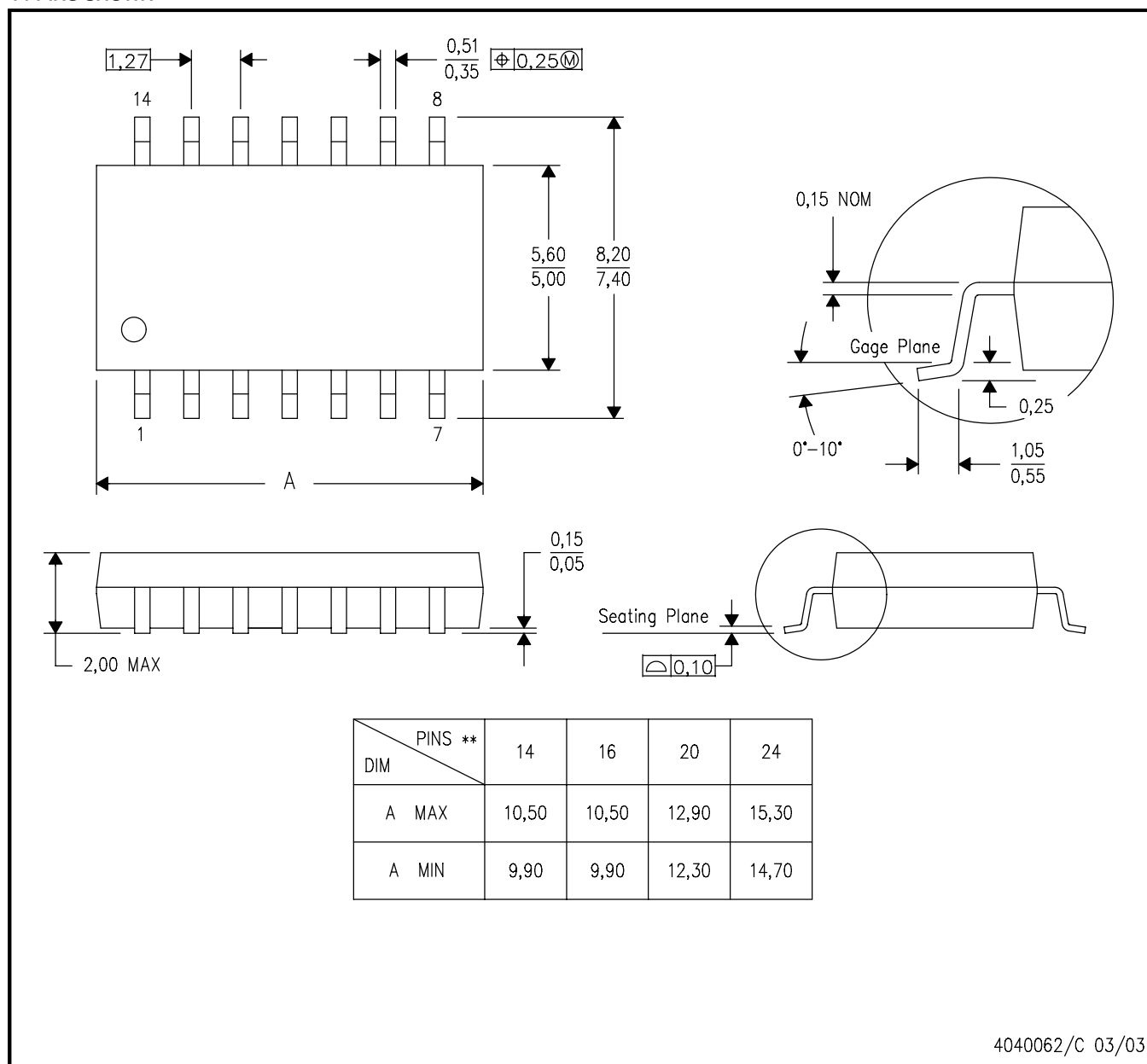
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-87624012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8762401DA	W	CFP	14	25	506.98	26.16	6220	NA
5962-8762401VDA	W	CFP	14	25	506.98	26.16	6220	NA
5962-8762402VDA	W	CFP	14	25	506.98	26.16	6220	NA
SN74AC14N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AC14N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AC14N	N	PDIP	14	25	506	13.97	11230	4.32
SN74AC14N	N	PDIP	14	25	506	13.97	11230	4.32
SNJ54AC14FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54AC14W	W	CFP	14	25	506.98	26.16	6220	NA

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

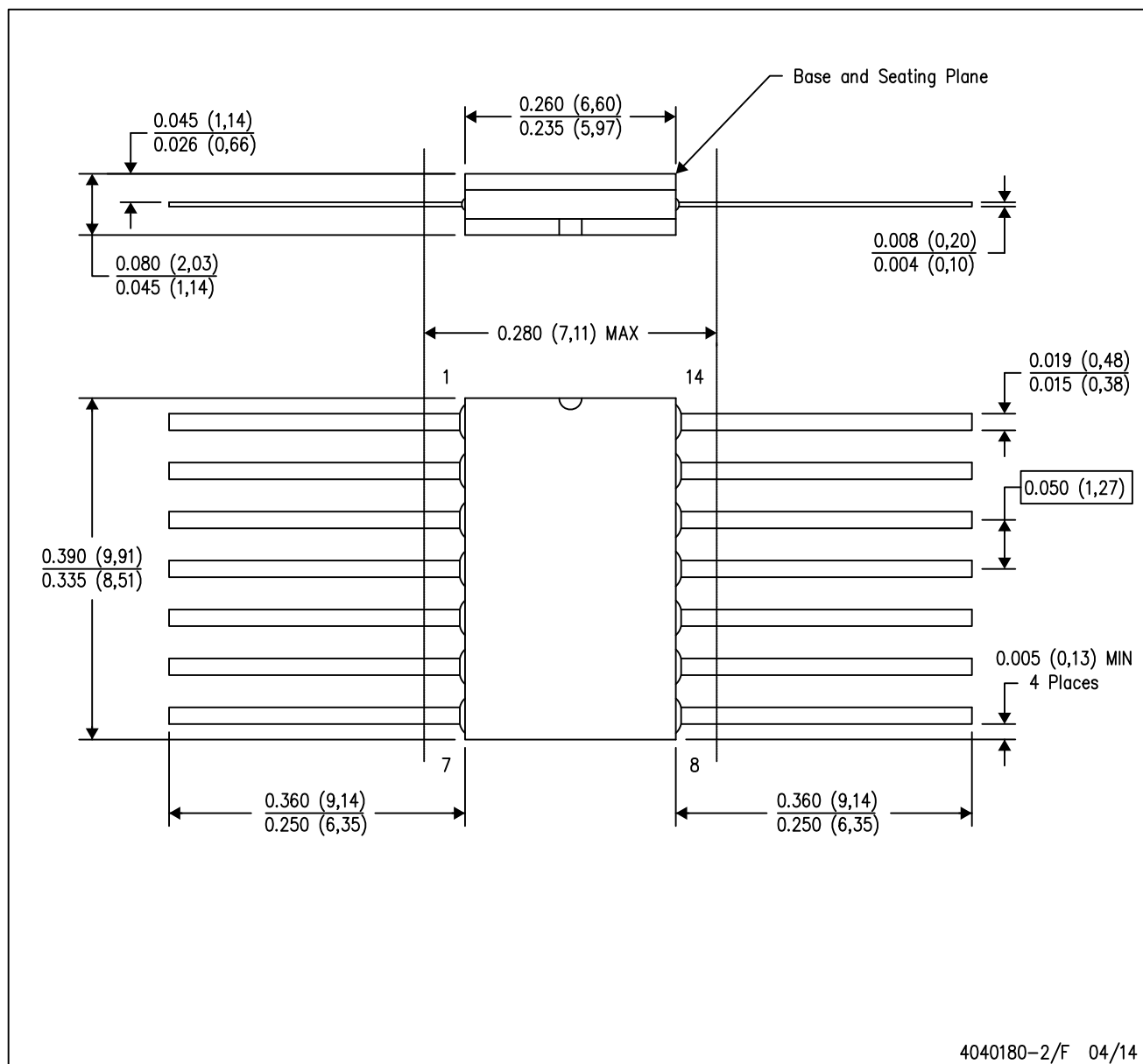
14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



GENERIC PACKAGE VIEW

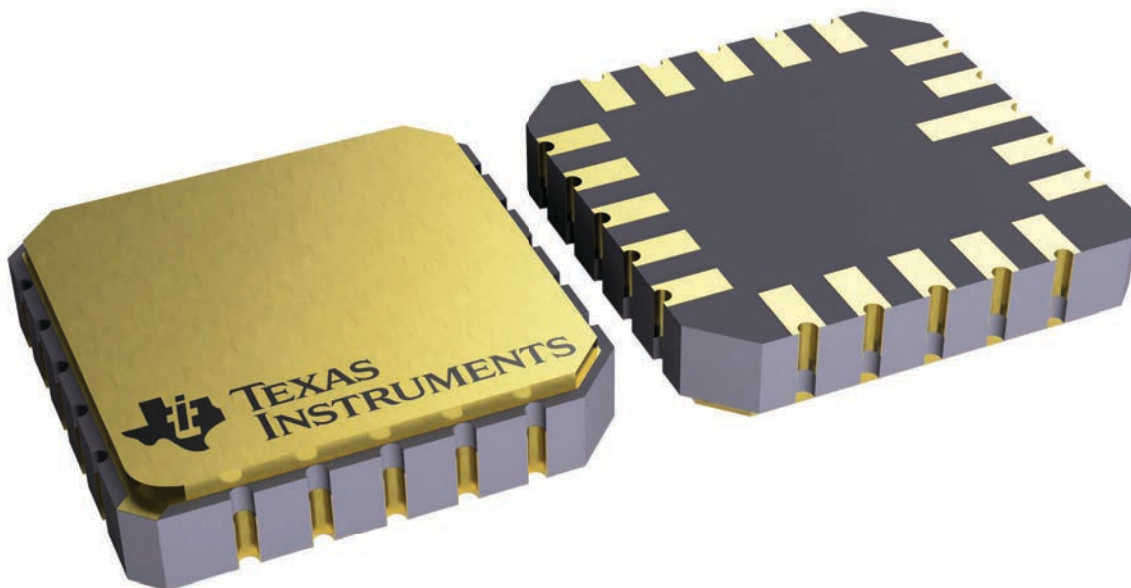
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



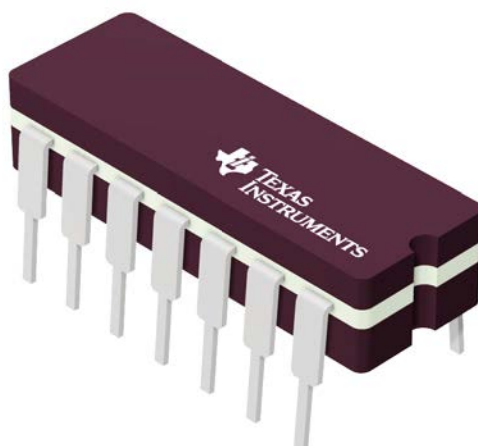
4229370VA\

J 14

GENERIC PACKAGE VIEW

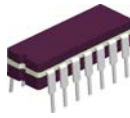
CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE

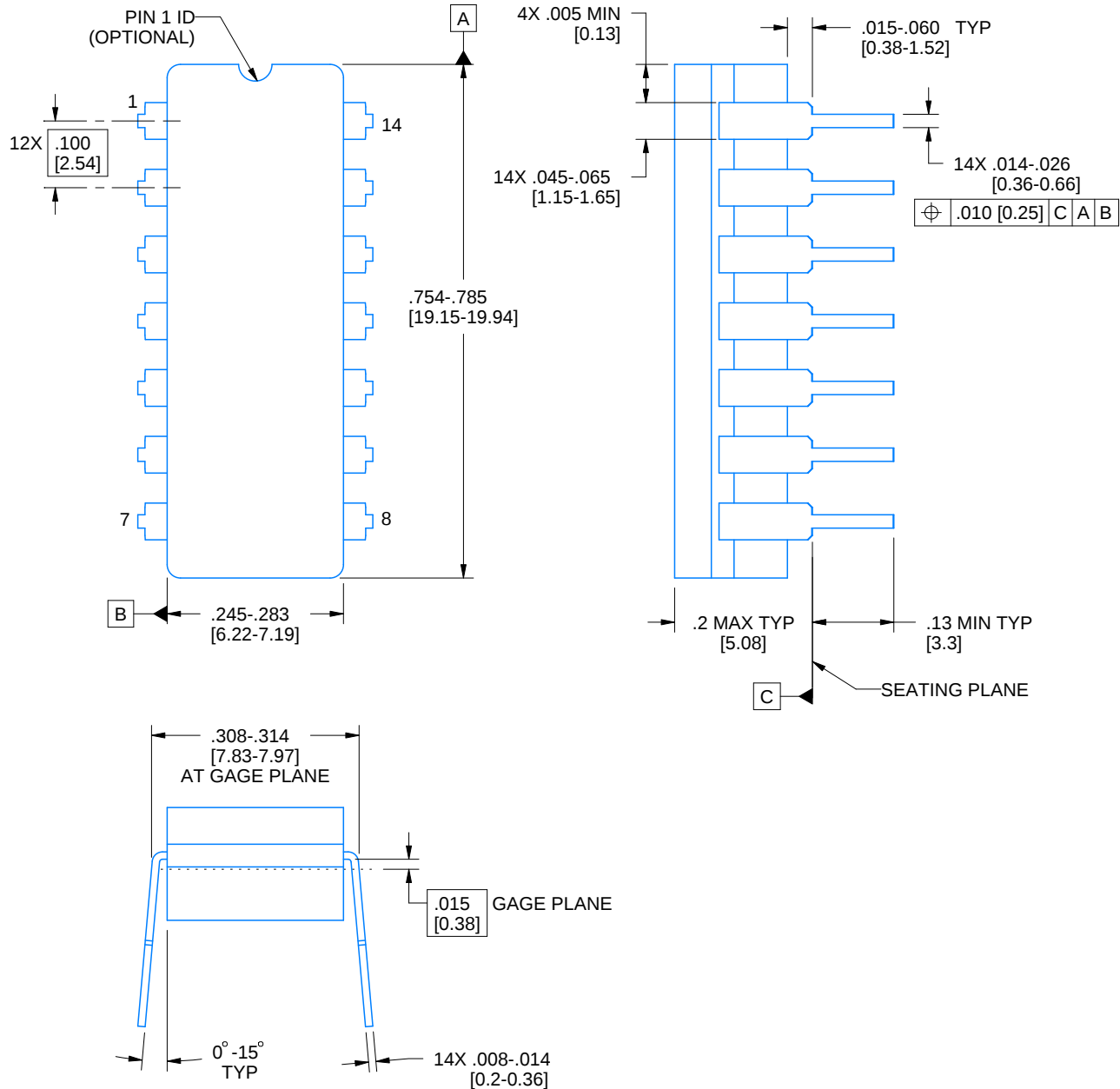


Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040083-5/G

J0014A**PACKAGE OUTLINE****CDIP - 5.08 mm max height**

CERAMIC DUAL IN LINE PACKAGE



4214771/A 05/2017

NOTES:

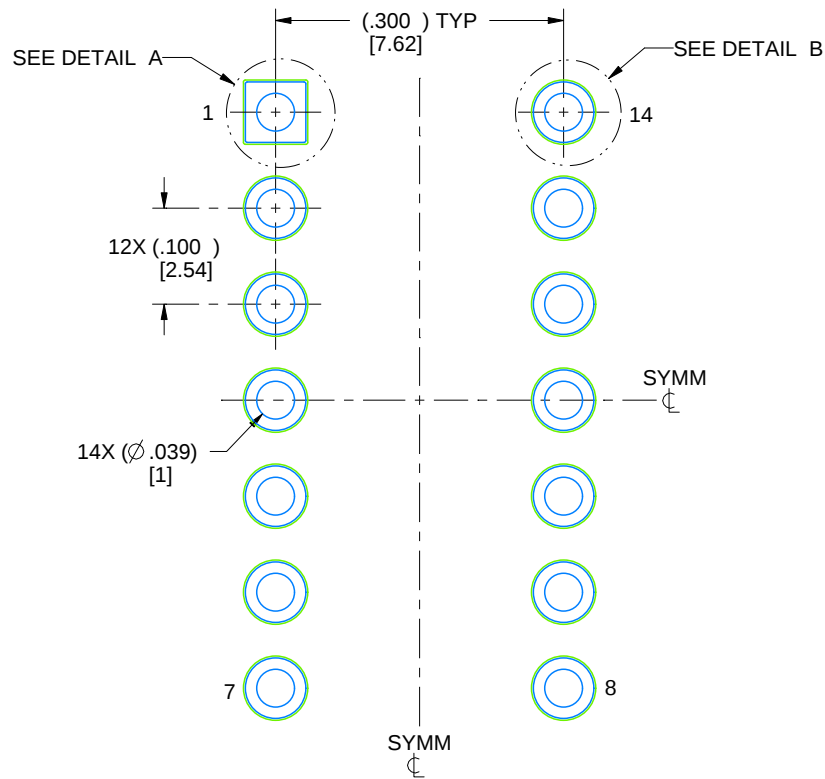
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a ceramic lid using glass frit.
4. Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
5. Falls within MIL-STD-1835 and GDIP1-T14.

EXAMPLE BOARD LAYOUT

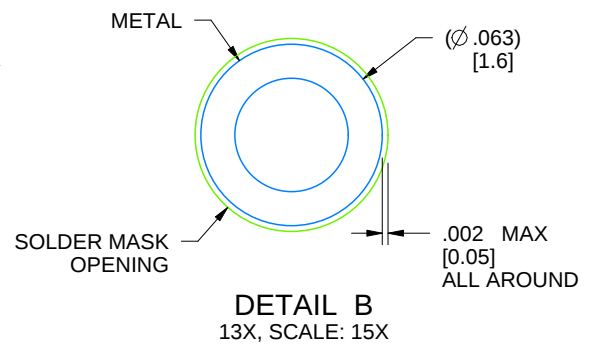
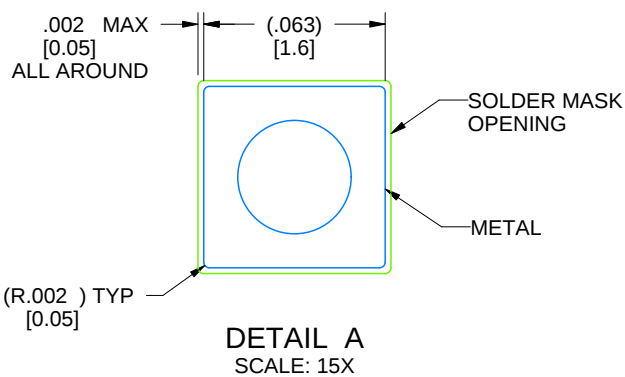
J0014A

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



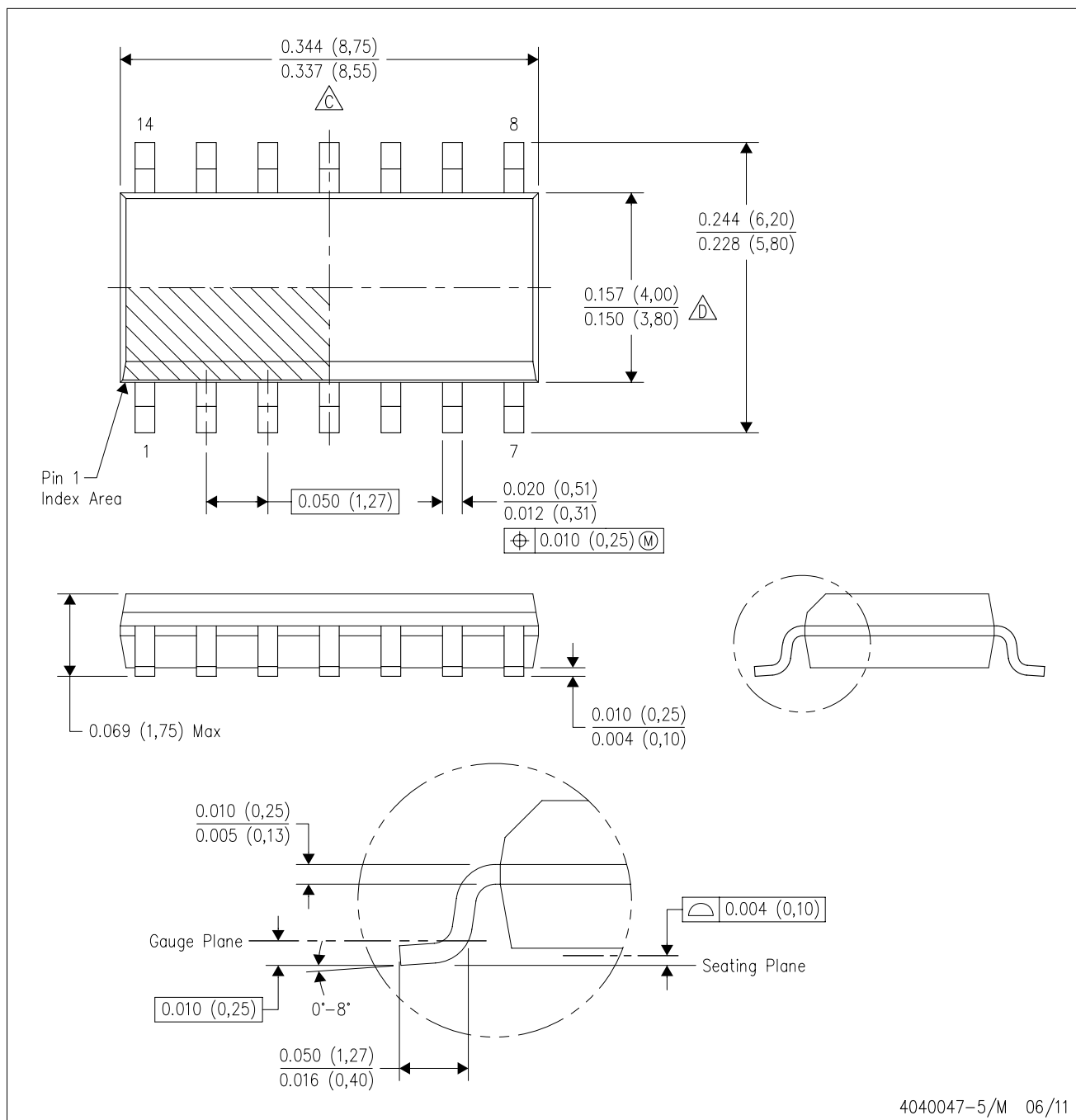
LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 5X



4214771/A 05/2017

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



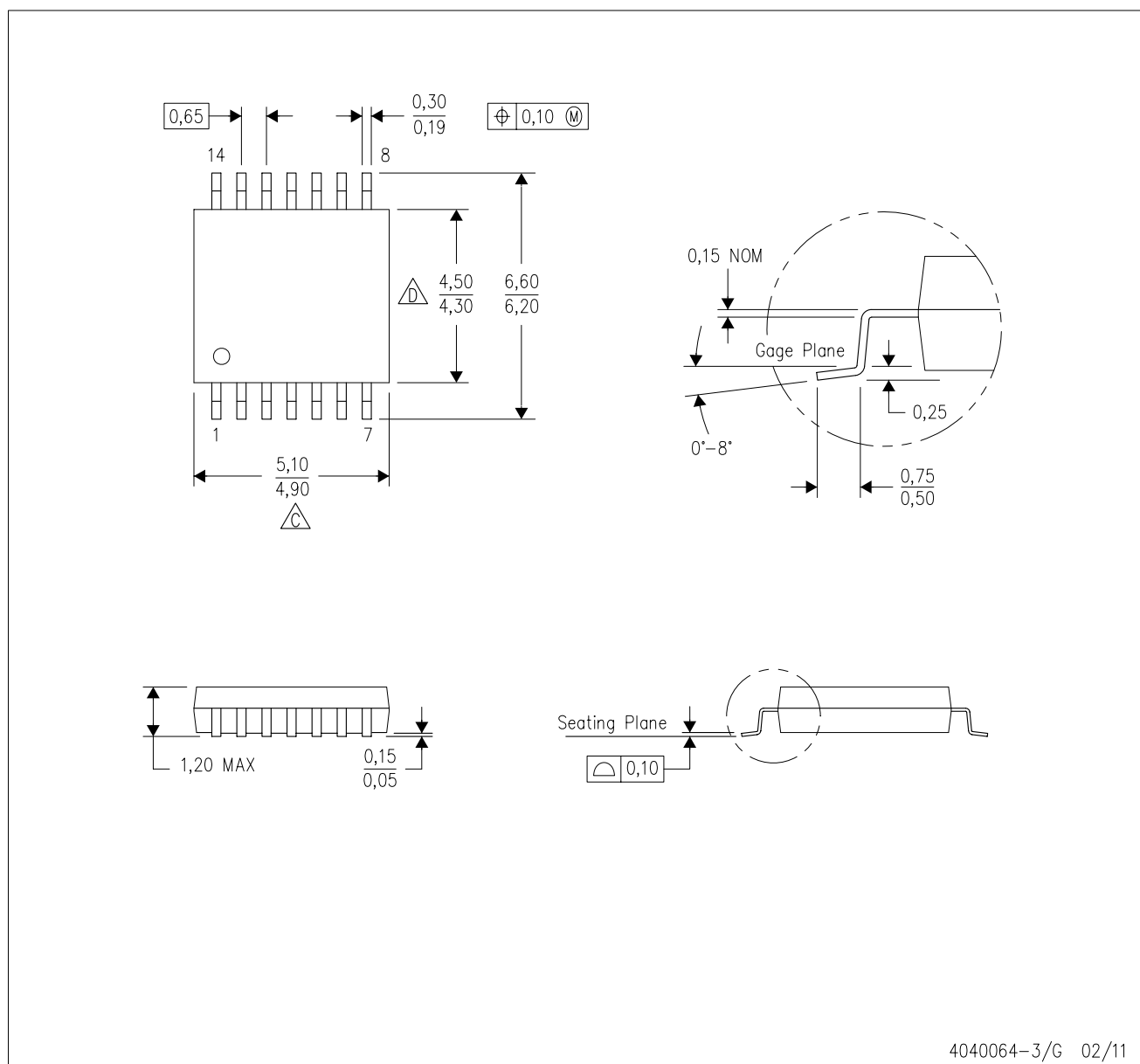
4040047-5/M 06/11

NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

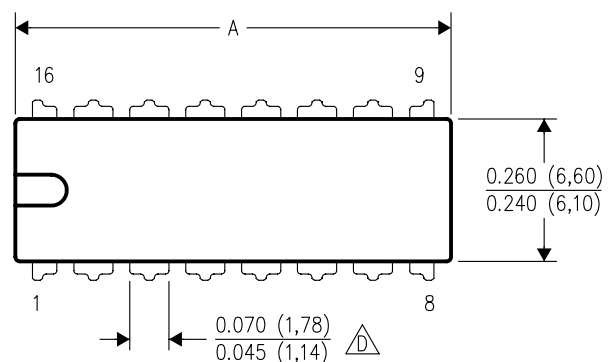


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

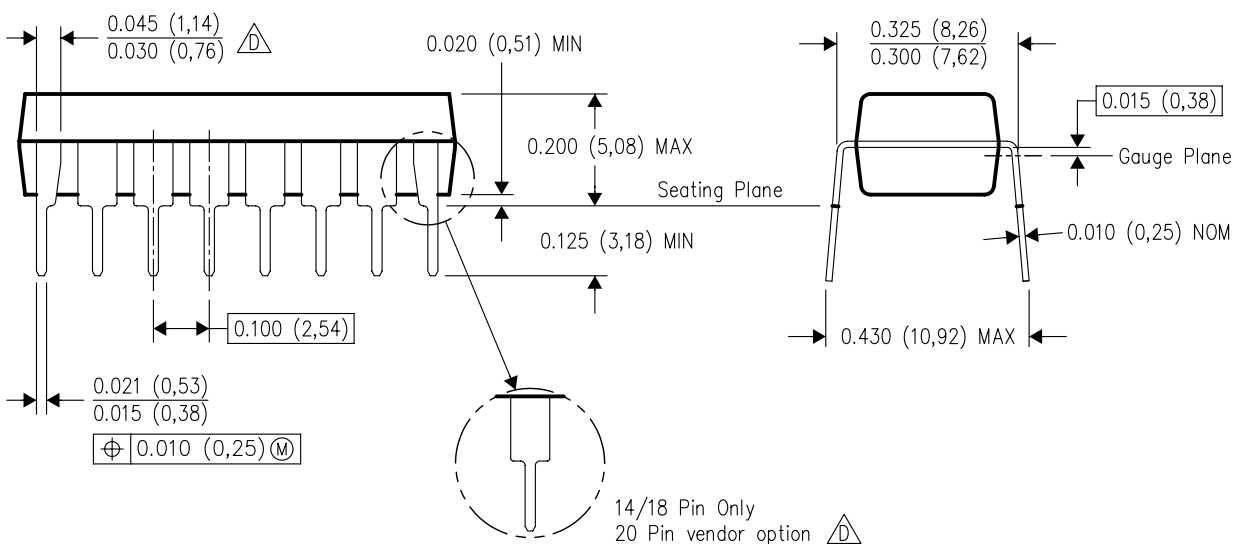
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

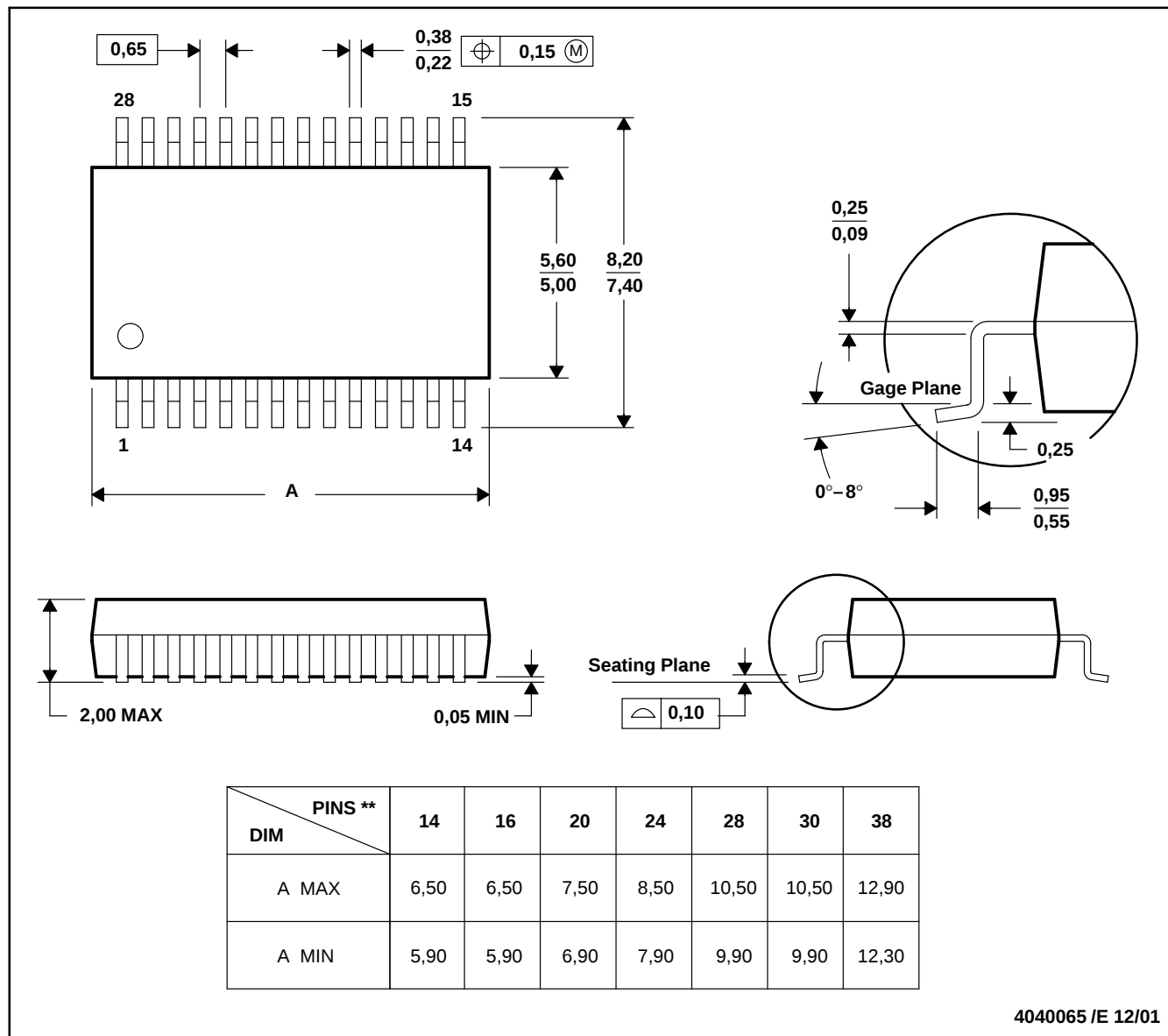
NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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